

EVVOSEMI[®]

THINK CHANGE DO



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

Product Specification

▶ Domestic	Part Number	NDS331N
▶ Overseas	Part Number	NDS331N-EV
▶ Equivalent	Part Number	NDS331N

EV is the abbreviation of name EVVO

N-Channel Enhancement Mode MOSFET

Description

The NDS331N uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

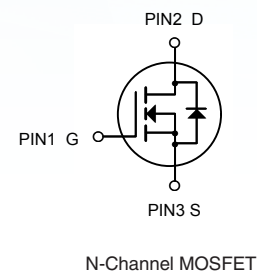
$V_{DS} = 20V$ $I_D = 2.3A$

$R_{DS(ON)} < 60m\Omega @ V_{GS}=4.5V$

Application

Battery protection
 Load switch
 Uninterruptible power supply

SOT-23



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
NDS331N	SOT-23	A2SHB	3000

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Drain Current-Continuous	2.3	A
I_{DM}	Drain Current-Pulsed (Note 1)	16	A
P_D	Maximum Power Dissipation	0.9	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 2)	139	$^\circ C/W$

N-Channel Enhancement Mode MOSFET

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	20	22	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =20V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±12V, V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.75	1.2	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =2.5V, I _D =2.0A	-	54	72	mΩ
		V _{GS} =4.5V, I _D =2.3A	-	48	60	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =2.3A	-	8	-	S
Input Capacitance	C _{iss}	V _{DS} =10V, V _{GS} =0V, F=1.0MHz	-	260	-	PF
Output Capacitance	C _{oss}		-	48	-	PF
Reverse Transfer Capacitance	C _{rss}		-	27	-	PF
Turn-on Delay Time	t _{d(on)}	V _{DD} =10V, R _L =3.3Ω V _{GS} =4.5V, R _{GEN} =6Ω	-	2.5	-	nS
Turn-on Rise Time	t _r		-	3.2	-	nS
Turn-Off Delay Time	t _{d(off)}		-	21	-	nS
Turn-Off Fall Time	t _f		-	3	-	nS
Total Gate Charge	Q _g	V _{DS} =10V, I _D =2.3A, V _{GS} =4.5V	-	2.9	5	nC
Gate-Source Charge	Q _{gs}		-	0.4	-	nC
Gate-Drain Charge	Q _{gd}		-	0.6	-	nC
Diode Forward Voltage ^(Note 3)	V _{SD}	V _{GS} =0V, I _S =2.3A	-	0.75	1.2	V
Diode Forward Current ^(Note 2)	I _S		-	-	3.3	A

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

N-Channel Enhancement Mode MOSFET

Typical Electrical and Thermal Characteristics

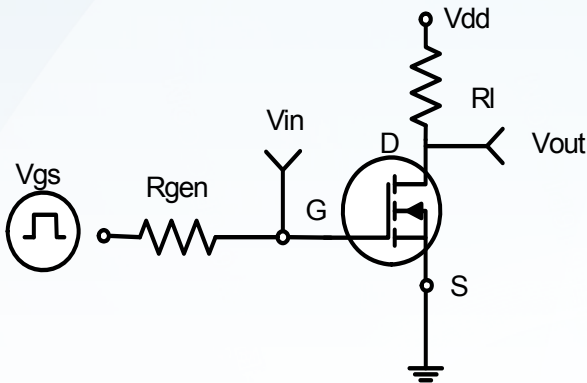


Figure 1: Switching Test Circuit

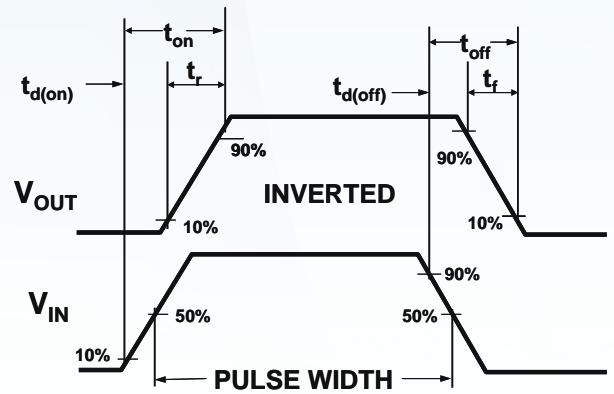


Figure 2: Switching Waveforms

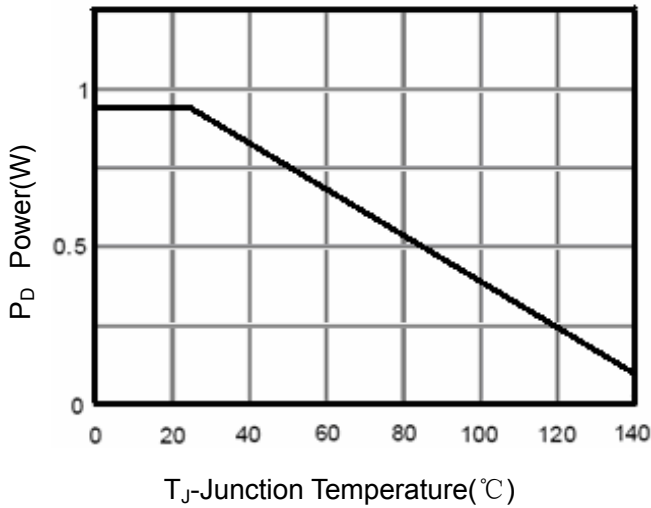


Figure 3 Power Dissipation

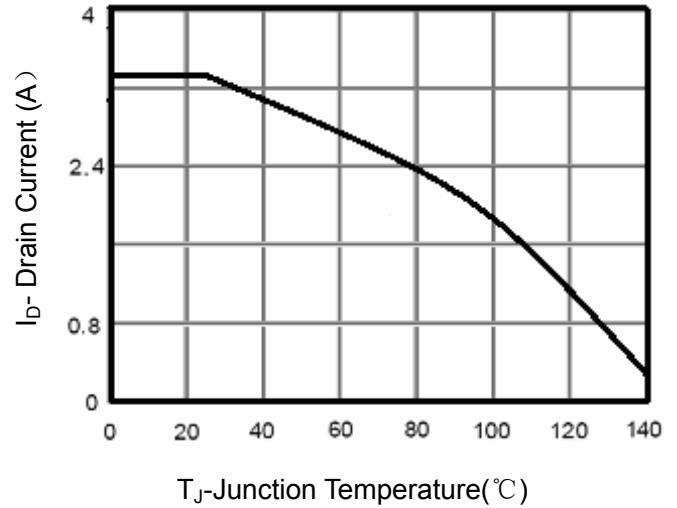


Figure 4 Drain Current

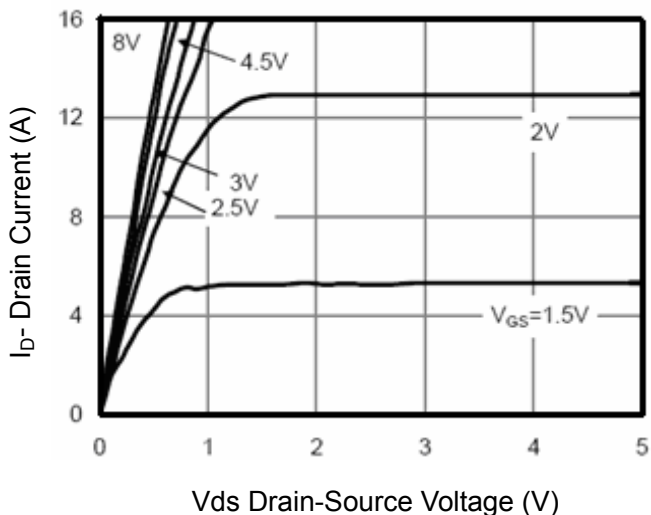


Figure 5 Output Characteristics

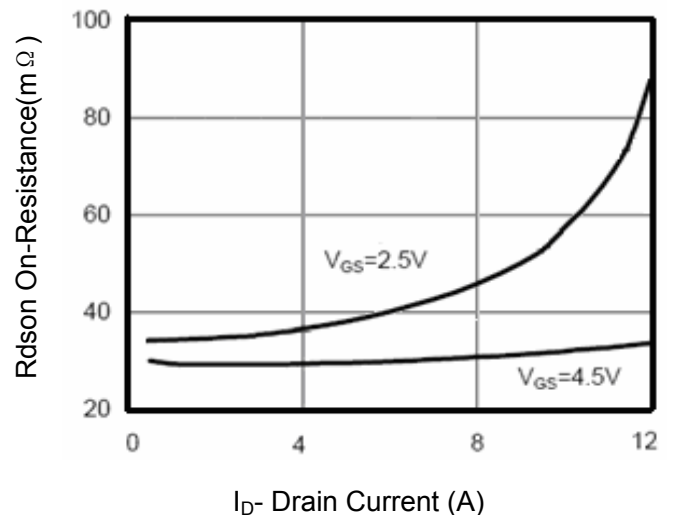


Figure 6 Drain-Source On-Resistance

N-Channel Enhancement Mode MOSFET

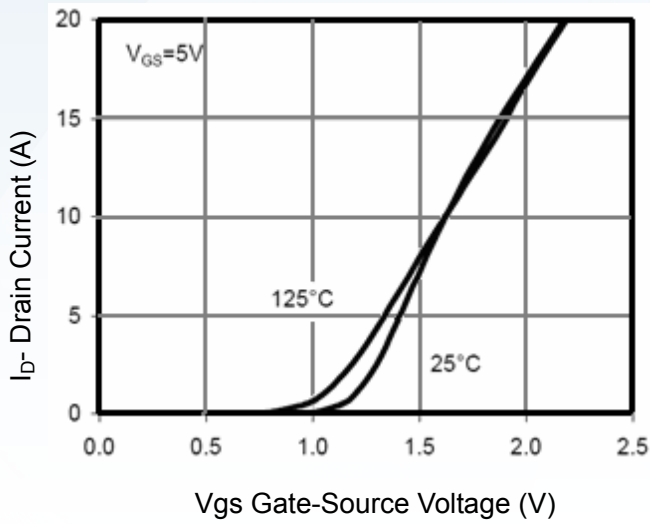


Figure 7 Transfer Characteristics

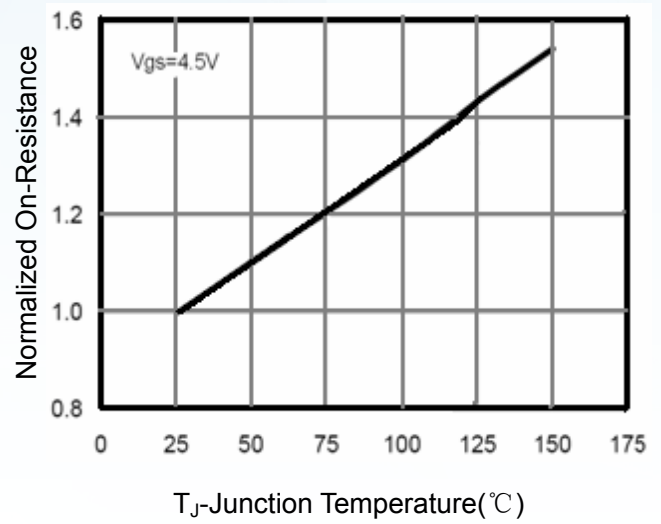


Figure 8 Drain-Source On-Resistance

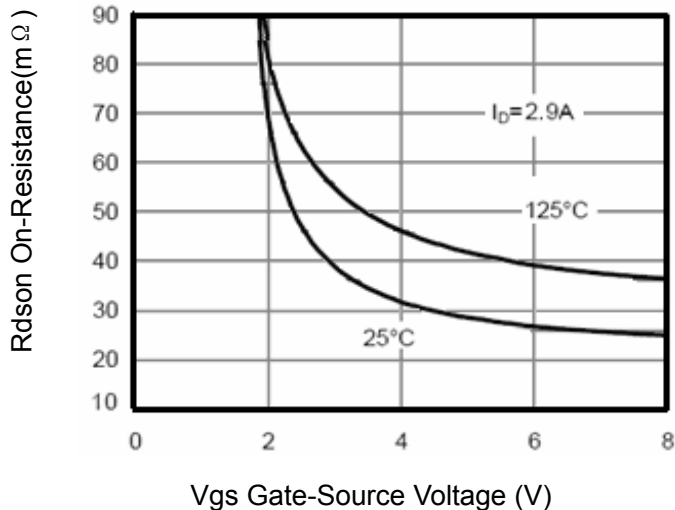


Figure 9 Rdson vs Vgs

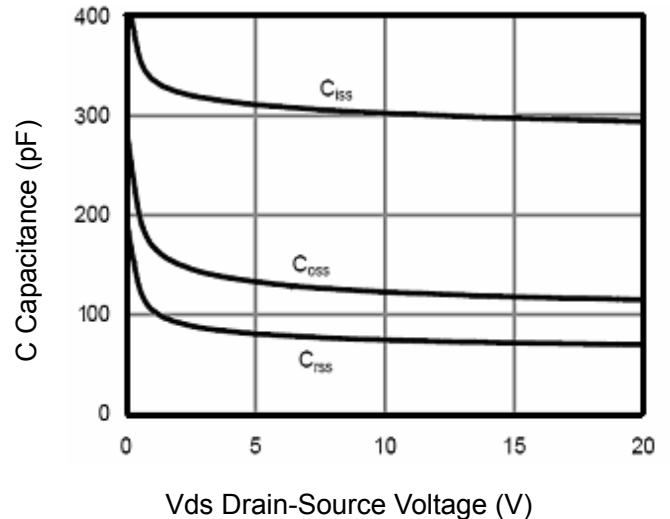


Figure 10 Capacitance vs Vds

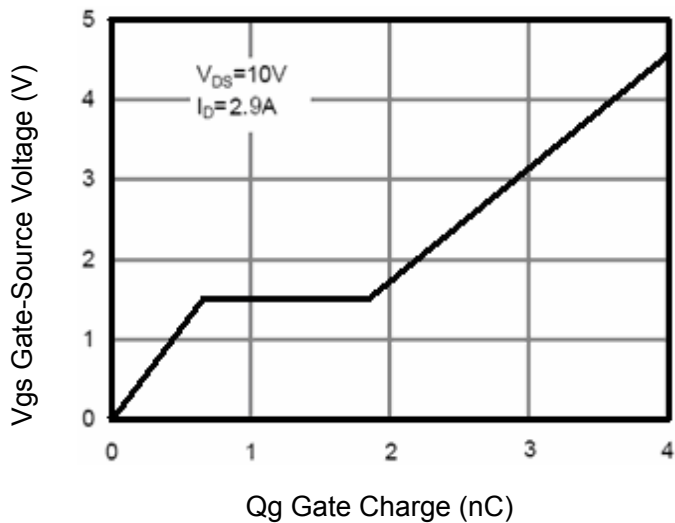


Figure 11 Gate Charge

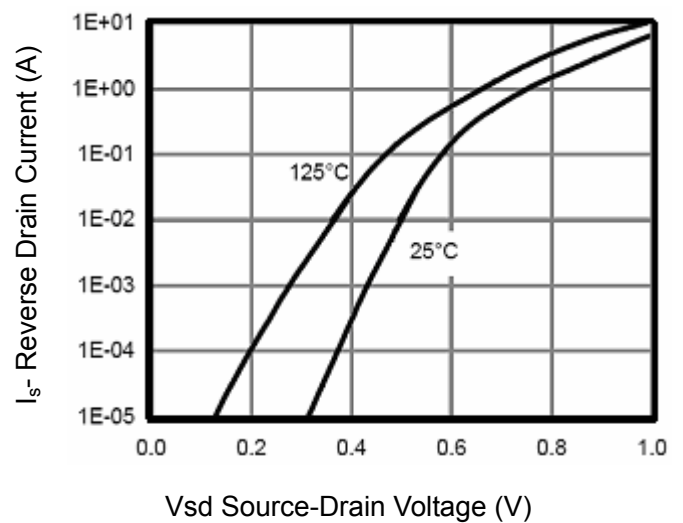
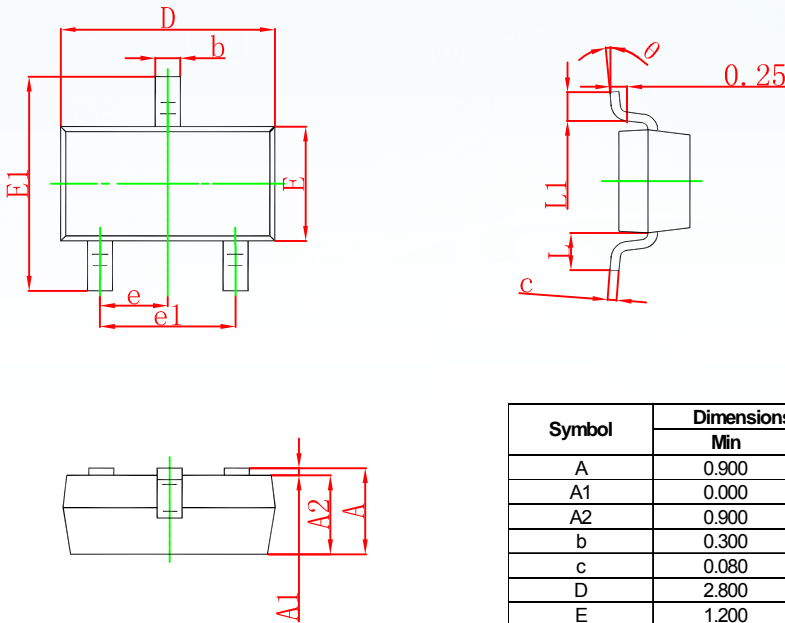


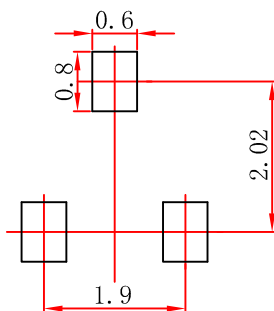
Figure 12 Source- Drain Diode Forward

SOT-23 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0° - 8°		0° - 8°	

SOT-23 Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.

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